



DATE: 19th Jan, 2016

PCN #: 2219

PCN Title: Additional FAB Source (TPSCo) and BOM (Bill of Materials) on select devices in SOT25 and MSOP8 packages

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 45 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2219 REV 00

| Notification Date: | Implementation Date: | Product Family: | Change Type: | PCN #: |
|---|---|------------------------|-------------------------------|---------------|
| 19 th Jan, 2016 | 29 th Feb, 2016 | Analog Semiconductors | Additional Fab Source and BOM | 2219 |
| TITLE | | | | |
| Additional FAB Source (TPSCo) and BOM (Bill of Materials) on select devices in SOT25 and MSOP8 packages | | | | |
| DESCRIPTION OF CHANGE | | | | |
| This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified additional wafer fab source (TPSCo) TowerJazz Panasonic Semiconductor Co., Ltd. located in Japan and BOM (Bill of Materials) on selected devices manufactured at (SAT) Diodes Incorporated / Shanghai Assembly/Test, China. Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. | | | | |
| IMPACT | | | | |
| Continuity of Supply. No change in datasheet parameters and product performance. | | | | |
| PRODUCTS AFFECTED | | | | |
| Table 1 Qualification of additional fab source (TPSCo) and BOM - Lead frame, die attach (Hysol 8008MD) for SOT25 package | | | | |
| Table 2 Qualification of additional fab source (TPSCo) and BOM - Lead frame, die attach (84-1LMISR4), wire type (0.8 mil Cu) and mold compound (CEL1700HF40SK-D3) for MSOP8 package | | | | |
| Table 3 Qualification of additional fab source (TPSCo) | | | | |
| WEB LINKS | | | | |
| Manufacturer's Notice: | http://www.diodes.com/quality/pcns | | | |
| For More Information Contact: | http://www.diodes.com/contacts | | | |
| Data Sheet: | http://www.diodes.com/products | | | |
| DISCLAIMER | | | | |
| Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved. | | | | |

| Table 1 - Qualify Additional Fab Source and BOM for SOT25 | | | |
|---|------------|-------------|--|
| AL8805W5-7 | AL8807W5-7 | AL8807AW5-7 | |

| Table 2 -Qualify Additional Fab Source and BOM for MSOP8 | | | |
|--|-------------|--------------|--|
| AL8806MP8-13 | AL8807MP-13 | AL8807AMP-13 | |

| Table 3 - Qualify Additional Fab Source | |
|---|--|
| AL8807BMP-13 | |